

IN THE CLAIMS:

Please CANCEL claim 22 without prejudice to or disclaimer of the recited subject matter.

Please AMEND claims 14, 15, 21, 56, 64, and 69, and ADD new claims 81-92, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1. (Previously Presented) An exposure apparatus, comprising:
  - a chamber surrounding a predetermined space;
  - a first gas supply unit for supplying a first gas into said chamber;
  - a second gas supply unit for supplying a second gas, different from the first gas, into said chamber, wherein the first and second gases contain substantially no oxygen; and
  - a switching mechanism for supplying one of the first and second gases by switching between said first and second gas supply units.
2. (Previously Presented) An exposure apparatus according to claim 1, wherein said chamber initially contains air, and the air in said chamber is replaced with the first gas, after which the first gas in said chamber is replaced with the second gas.
3. (Original) An exposure apparatus according to claim 1, wherein said switching mechanism is a switching valve.

4. (Original) An exposure apparatus according to claim 1, wherein an amount of the first gas supplied per unit time is different from an amount of the second gas supplied per unit time.

5. (Original) An exposure apparatus according to claim 1, wherein a flow path of the first gas in said chamber is different from a flow path of the second gas in said chamber.

6. (Previously Presented) An exposure apparatus, comprising:

- a chamber surrounding a predetermined space;
- a first gas supply unit for supplying a first gas into said chamber;
- a second gas supply unit for supplying a second gas, different from the first gas, into said chamber; and
- a switching mechanism for supplying one of the first and second gases by switching between said first and second gas supply units,

wherein said chamber includes a gas supply port for the first gas and a gas supply port for the second gas, and the gas supply port for the first gas is different from the gas supply port for the second gas.

7. (Previously Presented) An exposure apparatus, comprising:

- a chamber surrounding a predetermined space;
- a first gas supply unit for supplying a first gas into said chamber;

a second gas supply unit for supplying a second gas, different from the first gas,  
into said chamber; and

a switching mechanism for supplying one of the first and second gases by  
switching between said first and second gas supply units,

wherein said chamber includes a gas exhaust port for the first gas and a gas  
exhaust port for the second gas, and the gas exhaust port for the first gas is different from the gas  
exhaust port for the second gas.

8. (Previously Presented) An exposure apparatus, comprising:

a chamber surrounding a predetermined space;

a first gas supply unit for supplying a first gas into said chamber;

a second gas supply unit for supplying a second gas, different from the first gas,  
into said chamber; and

a switching mechanism for supplying one of the first and second gases by  
switching between said first and second gas supply units,

wherein said chamber includes a ventilation port for the first gas and a ventilation  
port for the second gas, and the ventilation port for the first gas is disposed differently from the  
ventilation port for the second gas.

9. (Original) An exposure apparatus according to claim 1, further comprising an  
illumination source for emitting a light beam having a wavelength in the vacuum ultraviolet

region, wherein said chamber partly surrounds a light path of the light beam emitted by the illumination source.

10. (Original) An exposure apparatus according to claim 9, wherein said illumination source is one of an F2 laser and an Ar2 laser.

11. (Original) An exposure apparatus according to claim 1, wherein said chamber contains an optical element.

12. (Original) An exposure apparatus according to claim 11, wherein said chamber contains a plurality of optical elements.

13. (Original) An exposure apparatus according to claim 1, further comprising an illumination optical system, wherein said chamber surrounds a light path in said illumination optical system.

14. (Currently Amended) An exposure apparatus according to claim 1, further comprising ~~an illumination~~ a projection optical system, wherein said chamber surrounds a light path in said projection optical system.

15. (Currently Amended) An exposure apparatus according to claim 1, further comprising ~~an illumination~~ a projection optical system, wherein said chamber surrounds said projection optical system.

16. (Cancelled)

17. (Original) An exposure apparatus according to claim 1, wherein the first and second gases have different specific gravities.

18. (Original) An exposure apparatus according to claim 1, wherein the second gas is an inactive gas.

19. (Original) An exposure apparatus according to claim 1, wherein the first gas is an inactive gas.

20. (Previously Presented) An exposure apparatus, comprising:

- a chamber surrounding a predetermined space;
- a first gas supply unit for supplying a first gas into said chamber;
- a second gas supply unit for supplying a second gas, different from the first gas, into said chamber; and

a switching mechanism for supplying one of the first and second gases by switching between said first and second gas supply units,

wherein the second gas is helium and the first gas is nitrogen.

21. (Currently Amended) A gas replacement method, comprising the steps of:

supplying a first gas into a chamber surrounding a predetermined space; and

supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,

wherein the first and second gases contain substantially no oxygen and one of the first gas and the second gas is supplied into the chamber by switching between a first gas supply unit for supplying the first gas and a second gas supply unit for supplying the second gas.

22. (Cancelled)

23. (Original) A gas replacement method according to claim 21, wherein a valve is used to switch between the first gas and the second gas.

24. (Previously Presented) A gas replacement method according to claim 21, wherein an amount of the first gas supplied per unit time is different from an amount of the second gas supplied per unit time.

25. (Original) A gas replacement method according to claim 21, wherein a flow path of the first gas in the chamber is different from a flow path of the second gas in the chamber.

26. (Previously Presented) A gas replacement method, comprising the steps of:  
supplying a first gas into a chamber surrounding a predetermined space; and  
supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,  
wherein a gas supply port for supplying the first gas in the chamber is different from a gas supply port for supplying the second gas in the chamber.

27. (Previously Presented) A gas replacement method, comprising the steps of:  
supplying a first gas into a chamber surrounding a predetermined space; and  
supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,  
wherein a gas exhaust port for exhausting the first gas from the chamber is different from a gas exhaust port for exhausting the second gas from the chamber.

28. (Previously Presented) A gas replacement method, comprising the steps of:  
supplying a first gas into a chamber surrounding a predetermined space; and  
supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,

wherein a ventilation port for the first gas in the chamber is disposed differently from a ventilation port for the second gas in the chamber.

29. (Original) A gas replacement method according to claim 21, wherein the chamber partly surrounds a light path of a light beam emitted from an illumination source, the light beam having a wavelength in the vacuum ultraviolet region.

30. (Original) A gas replacement method according to claim 29, wherein the illumination source is one of an F2 laser and an Ar2 laser.

31. (Original) A gas replacement method according to claim 21, wherein an optical element is contained in the chamber.

32. (Original) A gas replacement method according to claim 31, wherein a plurality of the optical elements are contained in the chamber.

33. (Original) A gas replacement method according to claim 21, wherein the chamber surrounds a light path in an illumination optical system of an exposure apparatus.

34. (Original) A gas replacement method according to claim 21, wherein the chamber surrounds a light path in a projection optical system of an exposure apparatus.



35. (Original) A gas replacement method according to claim 21, wherein the chamber surrounds a projection optical system of an exposure apparatus.

36. (Cancelled)

37. (Original) A gas replacement method according to claim 21, wherein the first and second gases have different specific gravities.

38. (Original) A gas replacement method according to claim 21, wherein the second gas is an inactive gas.

39. (Original) A gas replacement method according to claim 21, wherein the first gas is an inactive gas.

40. (Previously Presented) A gas replacement method, comprising the steps of:  
supplying a first gas into a chamber surrounding a predetermined space; and  
supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,  
wherein the second gas is helium and the first gas is nitrogen.

41. (Previously Presented) A method of manufacturing a semiconductor device, comprising the following steps:

- installing a group of manufacturing apparatuses, including the exposure apparatus of claim 1, for performing various processes in a semiconductor manufacturing factory; and
- manufacturing the semiconductor device through a series of the various processes using the group of manufacturing apparatuses.

42. (Previously Presented) A method of manufacturing a semiconductor device according to claim 41, further comprising the following steps:

- connecting the group of manufacturing apparatuses to one another through a local area network; and
- transmitting information as to at least one manufacturing apparatus of the group of manufacturing apparatuses between the local area network and an external network outside of the semiconductor manufacturing factory by means of a data communication link.

43. (Original) A method of manufacturing semiconductor devices according to claim 42, wherein maintenance information for at least one of the group of manufacturing apparatuses is obtained by accessing a database provided by a vendor or a user of the at least one manufacturing apparatus through the external network by means of the data communication link.

44. (Original) A semiconductor manufacturing factory, comprising:

- a group of manufacturing apparatuses for performing various processes including the exposure apparatus of claim 1;
- a local area network for connecting the group of manufacturing apparatuses to one another; and
- a gateway for permitting access from said local area network to an external network outside of the semiconductor manufacturing factory,

wherein information as to at least one manufacturing apparatus of said group of manufacturing apparatuses is transmitted by means of a data communication link.

45. (Previously Presented) A method of maintaining an exposure apparatus, comprising the steps of:

- providing maintenance for an exposure apparatus of claim 1, which is a database, connected to an external network of a semiconductor manufacturing factory;
- permitting access to the maintenance database from the semiconductor manufacturing factory through the external network; and
- transmitting information stored in the maintenance database to the semiconductor manufacturing factory through the external network.

46. (Original) An exposure apparatus according to claim 1, further comprising:

- a network interface; and

a computer network, accessible via the network interface,  
wherein information regarding the exposure apparatus is transmitted over the  
computer network by means of a data communication link.

47. (Previously Presented) An exposure apparatus according to claim 46, wherein a user  
or a vendor of the exposure apparatus can access a maintenance database provided by the other of  
the user or the vendor via an external network outside of a factory where the exposure apparatus  
is installed and obtain information from the maintenance database via the external network.

48. (Cancelled)

49. (Previously Presented) An exposure apparatus, comprising:  
a chamber surrounding a predetermined space;  
a first gas supply source for supplying a first gas into said chamber; and  
a second gas supply source for supplying a second gas, different from the first gas,  
into said chamber,  
wherein said chamber initially has a substantial oxygen content, but after the first  
gas and the second gas are sequentially supplied into said chamber, said chamber no longer has a  
substantial oxygen content,  
wherein the first gas is nitrogen and the second gas is helium.

50. (Previously Presented) An exposure apparatus, comprising:

a chamber surrounding a predetermined space;

a first gas supply source for supplying a first gas into said chamber; and

a second gas supply source for supplying a second gas, different from the first gas,  
into said chamber,

wherein said chamber initially has a substantial oxygen content, but after the first gas and the second gas are sequentially supplied into said chamber, said chamber no longer has a substantial oxygen content,

wherein the first gas is supplied into the chamber until the oxygen content in said chamber is reduced to less than about 0.00001 percent by volume, after which the second gas is supplied into said chamber until a concentration of the first gas in said chamber is reduced to less than about ten percent by volume.

51. (Previously Presented) An exposure apparatus, comprising:

a chamber surrounding a predetermined space;

a first gas supply source for supplying a first gas into said chamber; and

a second gas supply source for supplying a second gas, different from the first gas,  
into said chamber,

wherein said chamber initially has a substantial oxygen content, but after the first gas and the second gas are sequentially supplied into said chamber, said chamber no longer has a substantial oxygen content,

wherein the first gas is supplied into the chamber until the oxygen content in said chamber is reduced to about 0.000001 percent by volume or less, after which the second gas is supplied into said chamber until a concentration of the first gas in said chamber is reduced to about one percent by volume or less.

52. (Cancelled)

53. (Previously Presented) A method of reducing the oxygen content in a chamber that initially contains air, said method comprising the following steps:

first supplying a first gas into the chamber to substantially replace the air in the chamber;

next supplying a second gas, different from the first gas, into the chamber to substantially replace the first gas in the chamber,

wherein after the first gas and second gas have been sequentially supplied into the chamber, the chamber no longer has a substantial oxygen content,

wherein the first gas is nitrogen and the second gas is helium.

54. (Previously Presented) A method of reducing the oxygen content in a chamber that initially contains air, said method comprising the following steps:

first supplying a first gas into the chamber to substantially replace the air in the chamber;

next supplying a second gas, different from the first gas, into the chamber to substantially replace the first gas in the chamber,

wherein after the first gas and second gas have been sequentially supplied into the chamber, the chamber no longer has a substantial oxygen content,

wherein the first gas is supplied into the chamber until the oxygen content in the chamber is reduced to less than about 0.00001 percent by volume, and the second gas is supplied into the chamber until a concentration of the first gas in the chamber is reduced to less than about ten percent by volume.

55. (Previously Presented) A method of reducing the oxygen content in a chamber that initially contains air, said method comprising the following steps:

first supplying a first gas into the chamber to substantially replace the air in the chamber;

next supplying a second gas, different from the first gas, into the chamber to substantially replace the first gas in the chamber,

wherein after the first gas and second gas have been sequentially supplied into the chamber, the chamber no longer has a substantial oxygen content,

wherein the first gas is supplied into the chamber until the oxygen content in the chamber is reduced to about 0.000001 percent by volume or less, and the second gas is supplied into the chamber until a concentration of the first gas in the chamber is reduced to about one percent by volume or less.

56. (Currently Amended) An exposure apparatus comprising:

a chamber;

a first gas supply unit for supplying a first gas into said chamber; and

a second gas supply unit for supplying a second gas, different from the first gas,  
into said chamber,

wherein ~~said~~ the first gas has a higher molecular weight than ~~said~~ the second gas,  
a supply of ~~said~~ the first gas into said chamber starts before a supply of ~~said~~ the second gas into  
said chamber starts and the first gas and the second gas contain substantially no oxygen.

57. (Previously Presented) An exposure apparatus according to claim 56, wherein said  
first gas is nitrogen and said second gas is helium.

58. (Previously Presented) An exposure apparatus according to claim 57, wherein said  
first gas supply unit replaces atmosphere in said chamber with nitrogen, after which said second  
gas supply unit replaces the nitrogen with helium.

59. (Previously Presented) An exposure apparatus according to claim 57, wherein said  
first gas supply unit replaces air in said chamber with nitrogen, after which said second gas  
supply unit replaces the nitrogen with helium.



60. (Previously Presented) An exposure apparatus according to claim 56, wherein said first and second gases contain substantially no oxygen.

61. (Previously Presented) A device manufacturing method comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 56; and  
a developing process of developing the object to be exposed by using said exposure apparatus.

62. (Previously Presented) An exposure apparatus, comprising:  
a chamber;  
a nitrogen supply unit for supplying nitrogen into said chamber; and  
a helium supply unit for supplying helium into said chamber,  
wherein said nitrogen supply unit replaces atmosphere in said chamber with nitrogen, after which said helium supply unit replaces the nitrogen with helium.

63. (Previously Presented) A device manufacturing method comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 62; and  
a developing process of developing the object to be exposed by using the exposure apparatus.

64. (Previously Presented) A gas replacement method, comprising the steps of:

- a first supplying step for supplying a first gas into a chamber; and
- a second supplying step for supplying a second gas, different from the first gas,

into said chamber,

wherein said first gas has a higher molecular weight, said first supplying step starts before said second supplying step starts, and

wherein the first and second gases contain substantially no oxygen.

65. (Previously Presented) A gas replacement method according to claim 64, wherein said first gas is nitrogen and said second gas is helium.

66. (Previously Presented) A gas replacement method according to claim 64, wherein said first supplying step completes, after which said second supplying step starts.

67. (Previously Presented) A gas replacement method according to claim 64, wherein said first supplying step replaces atmosphere in said chamber with nitrogen, after which said second supplying step replaces the nitrogen with helium.

68. (Previously Presented) A gas replacement method according to claim 64, wherein said first supplying step replaces air in said chamber with nitrogen, after which said second supplying step replaces the nitrogen with helium.

69. (Currently Amended) A gas replacement method ~~according~~ according to claim 64, wherein said first and second gases contain substantially no oxygen.

70. (Previously Presented) A device manufacturing method comprising:  
a replacement process of replacing atmosphere in said chamber with said second gas by using a method according to the gas replacement method claimed in claim 64;  
an exposure process of exposing an object to be exposed by using optical elements disposed in said space; and  
a developing process of developing the object to be exposed by using the optical elements.

71. (Previously Presented) A gas replacement method, comprising the steps of:  
a first step for replacing atmosphere in a chamber with nitrogen; and  
a second step for replacing the nitrogen in said chamber with helium after said first step.

72. (Previously Presented). A device manufacturing method comprising:  
a replacement process of replacing atmosphere in said chamber with helium by using a method according to the gas replacement method claimed in claim 71;  
an exposure process of exposing an object to be exposed by using optical elements disposed in said space; and

a developing process of developing the object to be exposed by using the optical elements.

73. (Previously Presented) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 1; and  
a developing process of developing the object to be exposed.

74. (Previously Presented) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 6; and  
a developing process of developing the object to be exposed.

75. (Previously Presented) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 7; and  
a developing process of developing the object to be exposed.

76. (Previously Presented) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 8; and

a developing process of developing the object to be exposed.

77. (Previously Presented) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 20; and

a developing process of developing the object to be exposed.

78. (Previously Presented) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 49; and

a developing process of developing the object to be exposed.

79. (Previously Presented) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 50; and

a developing process of developing the object to be exposed.

80. (Previously Presented) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 51; and

a developing process of developing the object to be exposed.

81. (New) An exposing apparatus wherein a gas replacement is performed in accordance with the replacement method claimed in claim 21.

82. (New) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 81; and  
a developing process of developing the object to be exposed.

83. (New) An exposing apparatus wherein gas replacement is performed in accordance with the gas replacement method claimed in claim 26.

84. (New) A device manufacturing method, comprising:  
an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 83; and  
a developing process of developing the object to be exposed.

85. (New) An exposing apparatus wherein gas replacement is performed in accordance with the gas replacement method claimed in claim 28.

86. (New) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 85; and

a developing process of developing the object to be exposed.

87. (New) An exposure apparatus comprising:

a chamber;

a first gas supply unit for supplying a first gas into said chamber;

a second gas supply unit for supplying a second gas, different from the first gas, into said chamber; and

a switching mechanism for switching between a supply of the first gas from said first gas supply unit and a gas supply of the second gas from said second gas supply unit,

wherein the first gas has a higher molecular weight than the second gas, a supply of the first gas into said chamber starts before a supply of the second gas into said chamber starts and the first gas and the second gas contain substantially no oxygen.

88. (New) An apparatus according to claim 87, wherein the switching mechanism switches supply of said first gas from said first gas supply unit to supply of said second gas from said second gas supply unit.

89. (New) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 87; and

a developing process of developing the object to be exposed.

90. (New) A gas replacement method, comprising the steps of:

supplying a first gas into a chamber surrounding a predetermined space; and

supplying a second gas, different from the first gas, into the chamber, after the first gas is supplied,

wherein the first and second gases contain substantially no oxygen and the first gas is heavier than the second gas.

91. (New) An exposing apparatus wherein gas replacement is performed in accordance with the gas replacement method claimed in claim 90.

92. (New) A device manufacturing method, comprising:

an exposure process of exposing an object to be exposed by using the exposure apparatus claimed in claim 91; and

a developing process of developing the object to be exposed.